

a liquid phase film deposition chamber connected to said transferring chamber through a gate,

wherein said liquid phase film deposition chamber is provided with a mechanism for oxidizing an element belonging to Group 1 or 2 of the periodic table.

2. (Not Amended) A film deposition apparatus according to claim 1, wherein an inside of said transferring chamber is kept under a reduced pressure and said liquid phase film deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

3. (Not Amended) A film deposition apparatus according to claim 1, wherein said transferring chamber is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

4. (Not Amended) A film deposition apparatus comprising:
a stock chamber for loading or unloading a substrate;
a transferring chamber including a mechanism for transferring the substrate; and
a liquid phase film deposition chamber connected to said transferring chamber through a gate,

wherein said liquid phase film deposition chamber is provided with, via a piping, a mechanism for oxidizing an element belonging to Group 1 or 2 of the periodic table.

5. (Not Amended) A film deposition apparatus according to claim 4, wherein an inside of said transferring chamber is kept under a reduced pressure and said liquid phase film deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

6. (Not Amended) A film deposition apparatus according to claim 4, wherein said transferring chamber is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

7. (Not Amended) A film deposition apparatus comprising:
a stock chamber for loading or unloading a substrate;
two transferring chambers each connected to said stock chamber through a gate;
a vapor phase film deposition chamber connected to one of said two transferring chambers through a gate; and
a liquid phase film deposition chamber connected to another said transferring chamber through a gate,
wherein said liquid phase film deposition chamber is provided with a mechanism for oxidizing an element belonging to Group 1 or 2 of the periodic table.

8. (Currently Amended) A film deposition apparatus according to claim 7, wherein an inside of one of said transferring chambers is kept under a reduced pressure and said liquid phase film deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

9. (Currently Amended) A film deposition apparatus according to claim 7, wherein one of

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said transferring chambers is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

10 (Not Amended). A film deposition apparatus comprising:

a stock chamber for loading or unloading a substrate;

two transferring chambers each connected to said stock chamber through a gate;

a vapor phase film deposition chamber connected to one of said two transferring chambers through a gate; and

a liquid phase film deposition chamber connected to another said transferring chamber through a gate,

wherein said liquid phase film deposition chamber is provided with, via a piping, a mechanism for oxidizing an element belonging to Group 1 or 2 of the periodic table.

11. (Currently Amended) A film deposition apparatus according to claim 10, wherein an inside of one of said transferring chambers is kept under a reduced pressure and said liquid phase film deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

12. (Currently Amended) A film deposition apparatus according to claim 10, wherein one of said transferring chambers is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

13. (Previously Amended) A film deposition apparatus comprising:

a stock chamber for loading or unloading a substrate;

a transferring chamber for transferring said substrate; and

an EL material deposition chamber connected to said transferring chamber through a gate,

wherein said EL material deposition chamber is provided with a cell which contains an element belonging to Group 1 or 2 of the periodic table.

14. (Not Amended) A film deposition apparatus according to claim 13, wherein an inside of said transferring chamber is kept under a reduced pressure and said EL material deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

15. (Not Amended) A film deposition apparatus according to claim 13, wherein said transferring chamber is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

16. (Not Amended) A film deposition apparatus comprising:

a stock chamber for loading or unloading a substrate;

two transferring chambers each connected to said stock chamber through a gate;

a vapor phase film deposition chamber connected to one of said two transferring chambers through a gate; and

an EL material deposition chamber connected to another said transferring chamber through a gate,

wherein said EL material deposition chamber is provided with a cell which contains an element belonging to Group 1 or 2 of the periodic table.

17. (Currently Amended) A film deposition apparatus according to claim 16, wherein an inside of one of said transferring chambers is kept under a reduced pressure and said EL material deposition chamber is filled with an inert gas and is kept under atmospheric pressure or in a pressurized state.

18. (Currently Amended) A film deposition apparatus according to claim 16, wherein one of said transferring chambers is connected to a calcining chamber through a gate, and said calcining chamber is provided with a mechanism for turning said substrate upside down.

Claims 19-30 have been previously cancelled.

Please add the following claims:

31 (New) A film deposition apparatus according to claim 1,

wherein said liquid phase film deposition chamber is a chamber for depositing an EL material.

32 (New) A film deposition apparatus according to claim 1,

wherein said liquid phase film deposition chamber is provided with a spin coater for forming an EL layer.

33 (New) A film deposition apparatus according to claim 1,
wherein said liquid phase film deposition chamber is provided with a nozzle for forming an EL layer.

34 (New) A film deposition apparatus according to claim 4,
wherein said liquid phase film deposition chamber is a chamber for depositing an EL material.

35 (New) A film deposition apparatus according to claim 4,
wherein said liquid phase film deposition chamber is provided with a spin coater for forming an EL layer.

36 (New) A film deposition apparatus according to claim 4,
wherein said liquid phase film deposition chamber is provided with a nozzle for forming an EL layer.

37 (New) A film deposition apparatus according to claim 7,
wherein said liquid phase film deposition chamber is a chamber for depositing an EL material.

38 (New) A film deposition apparatus according to claim 7,
wherein said liquid phase film deposition chamber is provided with a spin coater for forming an EL layer.

39 (New) A film deposition apparatus according to claim 7,

wherein said liquid phase film deposition chamber is provided with a nozzle for forming an EL layer.

40 (New) A film deposition apparatus according to claim 10,
wherein said liquid phase film deposition chamber is a chamber for depositing an EL material.

41 (New) A film deposition apparatus according to claim 10,
wherein said liquid phase film deposition chamber is provided with a spin coater for forming an EL layer.

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42 (New) A film deposition apparatus according to claim 10,
wherein said liquid phase film deposition chamber is provided with a nozzle for forming an EL layer.

43 (New) A film deposition apparatus according to claim 13,
wherein said EL material deposition chamber is provided with a spin coater for forming an EL layer.

44 (New) A film deposition apparatus according to claim 13,
wherein said EL material deposition chamber is provided with a nozzle for forming an EL layer.

45 (New) A film deposition apparatus according to claim 16,

wherein said EL material deposition chamber is provided with a spin coater for forming an EL layer.

46 (New) A film deposition apparatus according to claim 16,
wherein said EL material deposition chamber is provided with a nozzle for forming an EL layer.

47 (New) A film deposition apparatus according to claim 1,
wherein said mechanism is provided with a lid.

48 (New) A film deposition apparatus according to claim 4,
wherein said mechanism is provided with a lid.

49 (New) A film deposition apparatus according to claim 7,
wherein said mechanism is provided with a lid.

50 (New) A film deposition apparatus according to claim 10,
wherein said mechanism is provided with a lid.

51 (New) A film deposition apparatus according to claim 13,
wherein said cell is provided with a lid.

52 (New) A film deposition apparatus according to claim 16,
wherein said cell is provided with a lid.